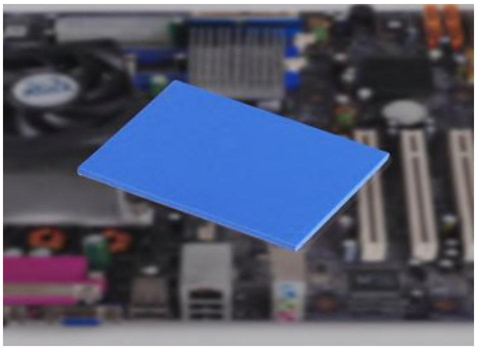
TP×× SF Series

Silicone Free Gap Filler Pad

TP××-SF series silicone-free thermal pads are designed for silicone sensitivity Sensing application and design, development of a high thermal conductivity, high Strength, flame retardant interface thermal conductive materials, for different The application of the development of a number of models can meet High compression, multiple heavy work, tear resistance, high frequency vibration Impact and other applications.



Features and Benefits

- 2.0 and 3.0 W/m.K options.
- Naturally tacky, easing application
- Excellent, high volume applications
- Excellent electrical isolation

Typical Applications

- Fiber Optics
- Medical Device
- Hard Disc Driver
- Automotive Sensors and Modules
- Silicon Sensitive Components

Typical Properties

Attribute	Value	Value	Test Method
	TP 200SF	**TP 300SF**	-
Composition	Acrylate	Acrylate	-
Color	Green	Blue	Visual
Thickness (mm)	1.0 to 3.0	1.0 to 10.0	ASTM D374
Density (g/cc)	2.8	3.0	ASTM D792
Hardness (Shore OO)	45	50	ASTM D2240
Usage Temperature (°C)	- 40 to 120	-40 to 125	–
Electrical			
Breakdown Voltage (kV/mm)	＞6.0	≥ 6.0	ASTM D149
Flammability	V-1	V-1	UL 94
Thermal			
Thermal conductivity (W/m.K)	2.0	3.0	ISO 22007-2

Storage

Store in a cool, dry, well-ventilated place.

Shelf life

Shelf life of the product is 12 months after date of shipment

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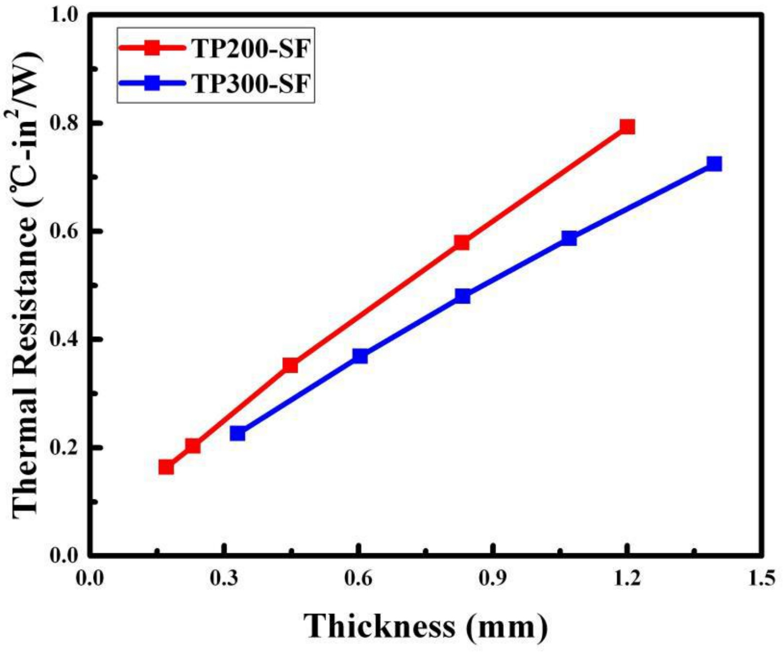
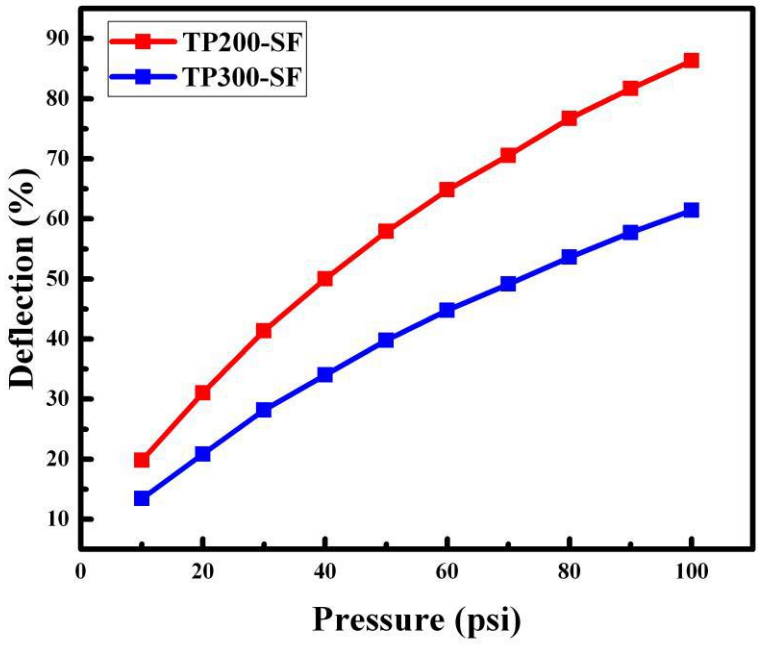
Thickness vs. Thermal Resistance

Referen



Pressure vs. Deflection

Reference



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